Features

- Fully integrated radio frequency/baseband/128MB memory single chip solution
- Supports FDD-TDD LTE Cat5/6/7
  - Cat5 LTE with 4x4 DL MIMO: 300Mbps DL, 75Mbps UL
  - Cat6 LTE with 4x2 carrier aggregation: 300Mbps DL, 50Mbps UL
  - Cat7 LTE with 4x4 MIMO or carrier aggregation with 300Mbps DL, 100Mbps UL
- Supports 4x4 DL-MIMO (4 layers) and 2x2 UL-MIMO (2 layers)
- 3GPP Release 10/11-compliant
- Supports eMBMS, OTDOA, TM8/9/10
- Single RF solution for FDD and TDD LTE
- Inter/Intra carrier aggregation (class C: 20+20MHz) for DL and UL
- Enhanced iCIC inter-cell interference cancellation
- Dual processor architecture: ARM Cortex-A7 with 832MHz clock frequency. Application CPU + Modem CPU (LTE)
- On-Chip VoLTE (HD-Voice)
- SoftAP for external WiFi client

Interfaces

- Host: SDIO3.0
- Device: SDIO3.0, USB3.0/USB2.0, RGMII
- USIM, I2S/PCM, NAND, SPI, UART

Package Outline

- 12x12x1.2 mm BGA package

Key Benefits

- LTE-Advanced
- Inter and Intra-Band CA
- World’s first 4x4 MIMO for LTE
- Low Power Consumption
- Fully Integrated (BB, RF), lower cost of ownership
- VoLTE, eMBMS, Routing function

Applications

- Smartphones
- Tablets
- Mobile Hotspots, CPEs
- Data cards
- M2M/IOT Modules
- Ultrabooks, Chromebooks
- Portable Multimedia Devices